	Туре	L#	Hits	Search Text	DBs	
1	BRS	L1	1648	257/784.ccls.	US-PGPUB; USPAT; USOCR	
2	BRS	L2	1535	257/777.ccls.	US-PGPUB; USPAT; USOCR	
3	BRS	L3	1827	257/723.ccls.	US-PGPUB; USPAT; USOCR	
4	BRS	L4	1802	257/686.ccls.	US-PGPUB; USPAT; USOCR	
5	BRS	L5	1578	257/786.ccls.	US-PGPUB; USPAT; USOCR	
6	BRS	L6	1971	257/773.ccls.	US-PGPUB; USPAT; USOCR	
7	BRS	L7	453	257/784.ccls.	EPO; JPO; DERWENT; IBM_TDB	
8	BRS	L8	134	257/777.ccls.	EPO; JPO; DERWENT; IBM_TDB	
9	BRS	L9	356	257/786.ccls.	EPO; JPO; DERWENT; IBM_TDB	
10	BRS	L10	0	((substrate or board) and wire and (first adj chip) and (second adj chip) and (first adj pad) and (third adj pad) and (pattern or wiring or trace)).clm.	US-PGPUB	
11	BRS	L11	0	((substrate or board) and wire and (first adj die) and (second adj pad) and (second adj pad) and (third adj pad) and (pattern or wiring or trace)).clm.	US-PGPUB	

}	Туре	L#	Hits	Search Text	D	Bs
12	BRS	L12	3	((substrate or board) and wire and (chip or die) and (first adj pad) and (second adj pad) and (third adj pad) and wiring or trace)).clm.	US-PGPUB	